

# Material Composition Specification

DO-201AD Case

Available with Pb(lead)-free plating\*



Device average mass .....1130mg  
Fluctuation margin ..... +/-10%

Device part	Substance	mass (mg)
active device	doped Si	3.20
leadframe	Copper Alloy	814
die attach	Pb92.5Ag2.5Sn5	2.05
*plating	SnPb10	7.76
	or Sn (100% tin, Pb-free)	7.76
encapsulation	epoxy molding compound  -silica  -epoxy < 20% -resin <10% -Sb <sub>2</sub> O <sub>3</sub> < 1.0%	303

\*Specify Lead-free when ordering 100% tin (Pb-free) plating option.